

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF : :

HIDEAKI YOSHIDA ET AL. : NEW APPLICATION DIVISION

SERIAL NO: NEW APPLICATION : :

FILED: HEREWITH : :

FOR: CONTACT PROBE AND PROBE  
DEVICE#5  
Paylandt-A  
4/19/83 T.BPRELIMINARY AMENDMENTASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Prior to a further examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel Claims 2-11 and 14-20 without prejudice:

Please amend Claims 1 and 12 as follows:

1. (Amended) In a probe device, an improved contact probe comprising:

a film;

a plurality of wiring patterns formed on a first surface of the film, each wiring pattern having a front end portion projecting out from the first surface of the film in a direction parallel to the first surface of the film so as to form contact pins; and

a metal layer provided on a second surface of the film,

wherein the plurality of contact pins include a fabricated bending point at a middle portion in an axial line direction with a Ni plating treatment.